

Please amend the application as follows:

IN THE TITLE:

At page 1, lines 1 - 2, please amend the Title as follows:

METHOD ~~AND APPARATUS~~ FOR CHEMICAL-MECHANICAL JET ETCHING OF
SEMICONDUCTOR STRUCTURES

IN THE SPECIFICATION:

At page 1, after the Title, please insert the following sentence:

-- This application is a divisional application of Application Serial No. 09/932,396, filed
August 17, 2001, which is currently pending. --